

Lam Research OnTrak Synergy



The Lam (OnTrak) DSS200 Post-CMP Double Sided Scrubber (DSS) is designed to clean wafers using options for a variety of chemical processes, including, but not limited to Post-CMP cleaning. The system is composed of multiple components which operate together to achieve processing requirements for semiconductor wafer cleaning.

The major system components include:

- ◆ Wet input station for automated wafer loading into the cleaner.
- ◆ Brush station #1 is the first brush stations the wafers enters in the processing cycle. The first scrub process is performed on PVA brushes using DI water and dilute cleaning chemistries.
- ◆ Brush station #2 is the second brush stations the wafers enters in the processing cycle. This scrub process also uses PVA brushes using DI water and dilute cleaning chemistries.
- ◆ The spin station is the third processing station: wafers receive a final rinse, followed by a spin dry in the SRD while a heat lamp assists in the completion of the drying process. This station may also include a dilute chemical dispense prior to final rinse.
- ◆ An unload hander/mechanical arm transports wafers out of the spin stations and to the output station.
- ◆ The output station contains a wafer indexer that receives the wafers from the transfer arm and loads the clean, dry wafers into a cassette for transfer to the next processing step.

Options:

- ◆ Wafer sizes: Configurable for 100 mm, 125 mm, 150 mm and 200 mm
- ◆ Remote Electrical Enclosure
- ◆ Megasonic Cleaning Unit
- ◆ Edge Cleaning in both brush boxes
- ◆ Chemical distribution (interchangeable for 2% NH_4OH , through the brush, 2% NH_4OH drip (standard configurations), and NH_4OH through-the brush)
- ◆ Through-the-back (TTB) Facilities Hookup
- ◆ Through-the-floor (TTF) Facilities Hook up
- ◆ Through-the-Front Wafer Load Input Station